

Applic. No. 09/916,056
Art Unit: 2839

AMENDMENTS TO THE CLAIMS:

Claim 1. (Currently Amended) An electronic connector, comprising:

a heat generating electronic component; and

a housing ~~surrounding and touching~~, which is molded over said heat generating electronic component; said housing being made of a thermally conductive material; said thermally conductive material being a net-shape injection moldable polymer composition with a base matrix of liquid crystal polymer material loaded with thermally conductive filler and having a thermal conductivity of at least 30 W/m²K; said housing being in thermal communication with said heat generating electronic component with heat dissipating from said heat generating electronic component and through said housing.

Claim 2. (Canceled)

Claim 3. (Canceled)

Claim 4. (Original) The electronic connector of Claim 1, wherein said heat generating electronic component is a semiconductor device.

Claim 5. (Original) The electronic connector of Claim 1, wherein said heat generating electronic component is a laser.

Claim 6. (Original) The electronic connector of Claim 1, wherein said electronic connector is an opto-electronic connector interface between fiber optic cable and electronic cable.

Claim 7. (Canceled)

Claim 8. (Previously Presented) The electronic connector of Claim 1, wherein said thermally conductive filler is selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium and brass.

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Claim 9. (Canceled)

Claim 10. (Canceled)

Claim 11. (Currently Amended) A method of forming an electronic connector, comprising the steps of:

providing a heat generating electronic component having a first port and a second port;

overmolding an outer housing of injection moldable thermally conductive polymer material, with a base matrix of liquid crystal polymer with filler therein, over and around said heat generating electronic component leaving said first port and said second port of said heat generating electronic component exposed.

Claim 12. (Canceled)

Claim 13. (Previously Presented) The method of Claim 11, wherein said filler is thermally conductive and selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium, nickel and brass.

Claim 14. (Canceled)

Claim 15. (Previously Presented) The method of Claim 11, wherein said filler material shields electromagnetic waves and is selected from the group consisting of aluminum, copper, alumina, magnesium and brass.

Claim 16. (Canceled)